

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	("6,671,174").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/12/03 10:12
L2	2	("6,628,779").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/12/03 10:29
S1	1	Modem adj module and carrier adj assembly and telephone adj line and solder adj pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 11:31
S2	3234	375/222.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 11:32
S3	1	S2 and motherboard and solder adj pad and modem and connector and ring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 11:33
S4	1	S2 and motherboard and solder adj pad and modem and printed adj circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 11:33
S5	1	S2 and motherboard and solder adj pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 11:34
S6	15	S2 and motherboard and modem and printed adj circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 11:34
S7	1	S6 and solder adj pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 11:34

S8	2	S6 and pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 11:34
S9	5	modem adj module and connector and motherboard and solder\$4 and connection	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:02
S10	39	modem adj module and connector and motherboard	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:51
S11	4	S10 and solder adj pads	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:51
S12	8267373	S10 and solder adj pads and MODEM MODULE MOUNT COMPRISE SOLDER PAD CONNECT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:53
S13	1	S10 and solder adj pads and MODEM adj MODULE adj MOUNT and SOLDER adj PAD adj CONNECT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:54
S15	1	solder adj pads and MODEM adj MODULE adj MOUNT and SOLDER adj PAD adj CONNECT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 13:55
S17	1	circuitry adj interfac\$3 and connecting adj modem and module adj carrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 14:06
S19	0	circuitry adj interfacin and connection and carrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 15:54
S20	87890	circuitry and connection and carrier	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 15:56

S21	3234	375/222.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 16:26
S22	1	S21 and motherboard and solder adj pad and modem and printed adj circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 16:26
S23	1	S21 and solder adj pad and modem and circuitry and printed adj circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 16:28
S24	1	S21 and solder adj pad and modem and circuitry	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 16:29
S25	865	S21 and modem and circuitry	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 16:30
S26	60	S25 and printed adj circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 16:31
S27	42	S21 and circuitry and motherboard	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 16:37
S28	240	circuitry adj interfac\$3 and modem and printed adj circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 17:46
S29	2	S28 and solder adj pads	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 17:46
S30	2501554	Motherboard ro Printed adj circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 18:07

S31	4317	S30 and solder adj pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 18:07
S32	1	S31 and modem adj assembly	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 18:08
S33	25	S30 and modem adj assembly	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 18:08
S34	1	S33 and solder adj pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 18:09
S35	22657	S30 and modem	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 18:11
S36	142	S35 and solder adj pads	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 18:11
S37	98	S36 and PCB	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 18:12
S38	30	S37 and telephone adj line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/19 18:12
S39	283029	printed adj circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 10:23
S40	122	S39 and modem adj circuitry	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 10:23

S41	9	S40 and solder adj pads	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 10:24
S42	9	S41 and telephone	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 10:24
S43	9	S41 and telephone adj line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 10:24
S44	2	S43 and ring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 10:25
S45	32	"4573753"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 11:53
S46	2	("4573753").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/20 11:54
S47	0	"input/output or I/O device"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 12:02
S48	0	("input/output or I/O device").OCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/20 12:02
S49	0	"input/output or I/O device"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 12:02
S50	0	"input/output or I/O device"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 12:03

S51	46033	"input/output device"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 12:03
S52	1545	S51 and motherboard	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 12:26
S53	694	S52 and slots	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 12:26
S54	13	S53 and "I/O cards"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 12:27
S55	33982	motherboard	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 12:36
S56	10528	S55 and slots	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 12:36
S57	312	S56 and "I/O cards"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 12:36
S58	24	S57 and receptacle	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 12:40
S59	1	"11416757"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 13:09
S60	8	"5788509"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/06/20 14:49

S61	2	("5788509").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/20 14:49
S62	2	("5990981").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/20 14:50
S63	2	("5,519,573").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/20 14:52
S64	2	("6,752,665").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/20 16:25
S65	3	"US 20020076038"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2009/07/31 15:10
S66	9	("2002/0076038").URPN.	USPAT	OR	ON	2009/07/31 15:10
S67	2	("4,766,402").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/07/31 15:12
S68	2	fabricating near3 modem near4 module	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/31 15:13
S69	7697	modem near4 module	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/31 15:14
S70	2	S69 and motherboard and solder adj pad and modem and connector and ring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/31 15:14
S71	6	S69 and motherboard and solder adj pad and modem	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/31 15:15

S72	6	S69 and motherboard and solder adj pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/31 15:16
S73	9	S69 and motherboard and solder and signal adj line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/31 15:16
S74	109	fabricating near3 modem	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/31 15:18
S75	1	S74 and solder and signal adj line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/31 15:18
S76	2	S74 and motherboard and solder adj pad and modem and connector and ring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/31 15:19
S77	2	S74 and motherboard and solder and modem and connector	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/31 15:20
S78	2	S74 and motherboard and modem and connector	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/31 15:20
S79	2	S74 and motherboard and modem	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/31 15:20
S80	6737	modem and circuitry and printed adj circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/31 15:22
S81	100	S80 and solder adj pad and modem	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/31 15:23



S82	19	method near4 fabricating near4 modem	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/31 15:23
S83	4	S81 and S82	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/31 15:23
S84	5	("2002/0172969").URPN.	USPAT	OR	ON	2009/07/31 15:25
S85	2	"US 20050190824"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2009/07/31 15:53
S86	2	"US 20090016040"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2009/08/03 09:51
S87	2	("4767344").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/08/03 09:59
S88	2	("4,767,344").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/08/03 11:31
S89	2	("6,078,661").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/07/05 08:53
S90	127399	Carrier same assembly	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 08:55
S91	1184	S90 and telephone same line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 08:55
S92	3	S91 and "tip/ring"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 08:56
S93	16	S91 and integrated same device and modem and printed adj circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 08:58

S94	1	S93 and "tip/ring"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 08:58
S95	1	S89 and tip same ring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 08:58
S96	1	S89 and tip same4 ring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 08:59
S97	1	S89 and tip and ring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 08:59
S98	1	S89 and ring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 08:59
S99	6	S91 and integrated same device and modem and printed adj circuit adj board and pads	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 08:59
S100	2	S99 and ring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 09:00
S101	1	S89 and connector and tip same ring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 09:01
S102	6	S91 and integrated same device and modem and printed adj circuit adj board and pads	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 09:02
S103	6	S102 and telephone	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 09:02

S104	2	S103 and ring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 09:02
S105	2	S103 and tip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 09:03
S106	0	("2005/0190824").URPN.	USPAT	OR	ON	2010/07/05 09:03
S107	74	solder adj pads and integrated same device and modem and printed adj circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 09:05
S108	17	S107 and modem and signal adj line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 09:06
S109	1	S108 and telephone adj line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 09:07
S110	4	S108 and telephone	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 09:07
S111	2	("5,015,813").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/07/05 09:12
S112	150	signal same line and solder same pads and integrated same device and modem and printed adj circuit adj board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 09:14
S113	31	S112 and connector same interface and modem and solder same pads	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 09:15
S114	2	S113 and signal same line same connect\$4 with solder same pads	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/05 09:17

S115	2	("20050141206").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/07/05 09:20
S116	2	("6,078,661").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/07/05 09:45
S117	2	"US 20050190824"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2010/07/12 10:23
S118	0	("2005/0190824").URPN.	USPAT	OR	ON	2010/07/12 10:23
S119	56581	"Tip/ring" or "telephone line" or "ground side" or "positive" and "Ring or "battery" or "negative and "phone circuit"	USPAT	OR	ON	2010/07/12 10:25
S120	8823	Tip near2 ring and "telephone line" or "ground side" or "positive" and "Ring or "battery" or "negative and "phone circuit"	USPAT	OR	ON	2010/07/12 10:26
S121	79	S120 and solder same pad	USPAT	OR	ON	2010/07/12 10:29
S122	4	S121 and tip same ring same connector	USPAT	OR	ON	2010/07/12 10:31
S123	7845	tip same ring same lines	USPAT	OR	ON	2010/07/12 10:53
S124	0	S123 and solder same pad and modem same module and tip same ring same connector and carrier	USPAT	OR	ON	2010/07/12 10:57
S125	2954	S123 and Tip near2 ring and "telephone line"	USPAT	OR	ON	2010/07/12 10:58
S126	43	S125 and circuitry near2 interfacing	USPAT	OR	ON	2010/07/12 10:59
S127	11	S126 and telephone same line and integrated same device	USPAT	OR	ON	2010/07/12 11:01
S128	0	S122 and motherboard	USPAT	OR	ON	2010/07/12 14:51
S129	10	S126 and motherboard	USPAT	OR	ON	2010/07/12 14:51
S130	4	S127 and S129	USPAT	OR	ON	2010/07/12 14:51
S131	14	S123 and printed adj circuit adj board near2 motherboard	USPAT	OR	ON	2010/07/12 15:43

S132	0	S131 and solder same pads	USPAT	OR	ON	2010/07/12 15:44
S133	5665	S131 and Tip near2 ring and "telephone line" or "ground side" or "positive" and "Ring or "battery" or "negative and "phone circuit"	USPAT	OR	ON	2010/07/12 15:45
S134	14	S131 and Tip near2 ring	USPAT	OR	ON	2010/07/12 15:45
S135	13	S134 and "telephone line"	USPAT	OR	ON	2010/07/12 15:45
S136	82	Modem adj module and telephone adj line and pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/16 14:25
S137	13	S136 and motherboard and "RJ11"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/16 14:26
S138	0	("2005/0190824").URPN.	USPAT	OR	ON	2010/07/16 14:27
S139	322	Modem adj module and telephone adj line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/16 14:28
S141	136	S139 and (tip or ring)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/16 14:28
S142	44	S141 and Modem same module and telephone adj line and pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/07/16 14:29
S143	2	((BRAD) near2 (GRANDE)). INV.	USPAT	OR	ON	2010/09/09 11:10
S144	5	("4008427"   "5799069"   "5995381"   "6212226"   "6624635").PN. OR ("7499539").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/09 11:13
S145	2	"US 20050190824"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2010/09/09 11:15
S146	1	("modem assembly") with solder same pads and tip and ring	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/09 11:19
S147	1	("modem") with solder same pads and tip and ring	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/09 11:20

S148	5	("modem") with solder and tip and ring	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/09 11:20
S149	0	("modem") with solder near10 connect\$2 same signal and tip and ring	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/09 11:24
S150	0	("modem") with solder near10 connect\$2 same signal and tip and ring	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/09 11:24
S151	0	("modem") with solder near10 connector same signal and tip and ring	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/09 11:24
S152	0	("modem") with solder near10 connecting same signal and tip and ring	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/09 11:25
S153	0	("modem") with solder same pads near10 connecting same signal and tip and ring	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/09 11:25
S154	0	(modem) with (solder same pads) near10 connecting same signal and tip and ring	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/09 11:26
S155	4	((modem) with (solder same pads))	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/09 11:26
S156	0	S155 and connecting same signal and tip and ring	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/09 11:26
S157	1	S155 and signal and tip and ring	US-PGPUB; USPAT; USOCR	OR	ON	2010/09/09 11:27
S158	2	("7499539").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/11/23 08:41
S159	2	("7773733").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/11/23 08:43
S160	1	((RODNEY) near2 (MEHRLANDER)).INV.	US-PGPUB; USPAT	OR	ON	2010/11/23 08:44
S161	6	((BRAD) near2 (GRANDE)).INV.	US-PGPUB; USPAT	OR	ON	2010/11/23 08:45
S162	46753	Modem same module	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 08:58
S163	9567	S162 and telephone same line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 08:59

S164	29	S163 and solder same pads	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 08:59
S165	55	S163 and ("tip/ring")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:00
S166	2	S165 and solder same pads	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:00
S167	3	S165 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:00
S168	13	("3239612"   "3497639"   "3515820"   "3692961"   "3692962"   "3700830"   "4021624"   "4255025"   "4255625").PN. OR ("4852144").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/11/23 09:02
S169	6154	S163 and (motherboard Pcb board carrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:12
S170	29	S169 and solder same pads	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:12
S171	43	S169 and ("tip/ring")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:13
S172	3	S171 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:13
S173	46753	Modem same module	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:14

S174	4403	S173 and modem same circuitry	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:14
S175	1980	S174 and (motherboard board PCB)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:14
S176	4	S175 and ("tip/ring")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:15
S177	1	S176 and pads	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:24
S178	553	S175 and pads	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:25
S179	1	S178 and ("tip/ring")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:25
S180	553	S175 and pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:25
S181	553	S178 and pads	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:25
S182	1	S181 and ("tip/ring")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:26
S183	68	S178 and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:26



S184	1	S183 and ("tip/ring")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:26
S185	114	(motherboard Pcb board carrier) and ("tip/ring") and pads	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:31
S186	56	S185 and telephone same line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:32
S188	225	(card modem) with (solder \$3 adj pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:42
S189	2	S188 and ("tip/ring")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:43
S190	6025	tip near ring and telephone near5 line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:44
S191	6025	(tip near ring) and (telephone near5 line)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:44
S192	2	S188 and S191	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:44
S193	3	S188 and (telephone near5 line)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 09:45
S194	155	361/760,767.ccls. and (solder adj pad) with (surface carrier board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:16

S195	0	S194 and rj11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:16
S196	155	S194 and (pad terminal land electrode contact)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:17
S197	0	S196 and Tip near ring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:17
S198	39	S196 and (connector)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:18
S199	6	S196 and modem	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:18
S200	1	S199 and (connector)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:19
S201	6	S194 and (pad terminal land electrode contact)and modem	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:20
S202	6	S194 and (pad terminal land electrode contact)and modem	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:24
S203	0	361/760,767.ccls. and RJ11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:25
S204	1429	361/760,767.ccls. and (Tip ring connector)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:25

S205	64	S204 and (solder adj pad) with (surface carrier board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:25
S206	1	S205 and (pad terminal land electrode contact) and modem	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:25
S207	0	S196 and telephone adj line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:32
S208	6	361/760,767.ccls. and telephone adj line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:33
S209	88	361/760,767.ccls. and modem	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:39
S210	76	S209 and (pad terminal land electrode contact) and modem	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:39
S211	6	S210 and (solder adj pad) with (surface carrier board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:39
S212	0	S211 and (RJ11)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:39
S213	1	S211 and connector	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:39
S214	84	(solder adj pad) with (surface carrier board) and modem	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:41

S215	84	(solder adj pad) with (surface carrier board)and modem and (pad terminal land electrode contact)and modem	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:41
S216	5276064	(solder adj pad) with (surface carrier board)and modem and (pad terminal land electrode contact)and modemand (Tip ring connector)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:42
S220	84	(solder adj pad) with (surface carrier board)and modem and (pad terminal land electrode contact)and modem	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:42
S221	8	(solder adj pad) with (surface carrier board)and modem and (pad terminal land electrode contact)and modem and telephone adj line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 10:43
S222	1	("2002/0001979").URPN.	USPAT	OR	ON	2010/11/23 12:47
S223	8158	(printed circuit board) with telephone near line	USPAT	OR	ON	2010/11/23 13:32
S224	1692	S223 and tip near ring	USPAT	OR	ON	2010/11/23 13:32
S225	1	S224 and (solder adj pad) with (surface carrier board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/11/23 13:32
S226	8	("4466688"   "5457593"   "5653601"   "6083032"   "6382989"   "6560126"). PN. OR ("6671174").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/11/23 13:56
S227	2	"US 20080240425"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2010/11/24 09:49
S228	2	"US 20080226081"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2010/11/24 09:59

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